

**Abstract:****Method for Locating Flaws, and a Marking System**

The present invention relates to a method and a marking system for locating flaws on a three-dimensional object (2), particularly on its surface, the defective points being  
5 detected and located using an optical picture-taking device (3,4). To locate a flaw with great accuracy, it is provided that the design data related to the object (2), the optical imaging properties of the picture-taking device (3,4), and the position of the optical picture-taking device (3, 4) and the object (2) are known when the picture is taken, and that the location of the flaw on the object (2) is determined and optionally marked.

10 (Figure 1)